Powering the Future: Harnessing 2kV SiC for a Decentralized Grid

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Sic

Bodo's Wide Bandgap Event 2024 Making WBG Designs Happen

Semikron Danfoss - highlights



Highlights

1,100 mEUR Sales in 2023 **∼4,000** Employees worldwide

The largest chip-independent manufacturer of power modules worldwide.

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28 Sites on 5 continents

Chip



The Energy Landscape

- Growth of renewables: increased incentives and reduction in carbon emissions
- Importance of ESS: grid stability, integration of solar & ESS
- Growth of EV charging: rise in EV adoption, need for charging infrastructure
- Interconnected grid based on $1500V_{\text{DC}}$

FIGURE 21 SOLAR PV ROOFTOP AND UTILITY-SCALE SEGMENTS SCENARIOS 2023-2027



650GW / 1,877GWh

Global cumulative energy storage capacity by the end of 2030



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Modular or Central PCS in ESS System



Low/medium-power system

Modular PCS (~210kW)

- Increasing trend for Battery ESS
- Improves serviceability, only subset of batteries offline in case of failure
- Better scalability, able to adjust by 210kW rather than changing entire PCS
- Matches 12 rack system for 2.5MW PCS

High-power system



Central Inverter (~2.5MW)

- Originally solution with similar hardware design as solar, achieving economy of scale
- Serviceability a challenge, major downtime with single failure
- Limited scalability, creating large power mismatch with batteries





Design Simplicity with 2kV SiC for $1500V_{\text{DC}}$ Applications

3-Level design

- 12 to 18 total driver channels
- Three-layer bus plate for DC-link
- Module positioning may be complex to minimize low stray inductance
- Multiple gate voltages if integrating silicon and SiC
- Optimization may be required for PF: -1 to eliminate de-rating



2-Level design

- Meets 1500V applications with ≥2000V chip rating
- Six total driver channels
- Single gate voltage
- 2-layer bus plate for DC-link
- Simple module layout on heatsink



DC+

Τ1

T2

DC-

Expanding the Power Module Portfolio

Low/medium-power system



High-power system



SEMITOP E2 with 2kV SiC

- Half-bridge variants with 4.3m Ω (200A) & 6.5m Ω (150A) R_{ds,on}
- Optimized pin layout for paralleling
- Increased isolation voltage

SEMITRANS 20 with 2kV SiC

- Half-bridge with $1m\Omega R_{ds,on}$ (1700A)
- Sintered for increased lifetime
- Symmetrical chip layout for optimal performance
- Improved substrates



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Low/medium-power system



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Low/Medium-Power Module: SEMITOP E2 with 2kV SiC





215kW PCS with liquid cooling

- 1x 200A power module per phase
- 1500V_{DC}, 690V_{AC}, 50Hz, fsw:12kHz, PF:±1
- 40°C coolant
- Power module efficiency: 99.1%
- T_{j,max}: 133°C

215kW PCS with air cooling

- 2x 150A power modules per phase
- 1500V_{DC}, 690V_{AC}, 50Hz, fsw:12kHz, PF:±1
- 40°C inlet airflow
- Power module efficiency: 99.1%
- T_{j,max}: 130°C





Modular or Central PCS in ESS System

Low/medium-power system					
BAT.	BAT.	BAT.	BAT.	BAT.	BAT.
BAT.	BAT.	BAT.	BAT.	BAT.	BAT.
PCS	PCS	PCS	PCS	PCS	PCS
PCS	PCS	PCS	PCS	PCS	PCS

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High-Power Modules for 1500V_{DC} Applications



Power Density Comparison: Maximum current per power module area



The 2kV SiC solution provides over 2 times current for a given area

- Leading to smaller, more power dense PCS
- Reduced losses for 2kV SiC compared to silicon support increase in power density

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High-Power: Power Density Comparison 1500V_{DC}, 690V_{AC}, 5kHz $f_{SW,effective}$, Liquid Cooling

1.2MW



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0000

0

1MW



ST10 TNPC (2.3kV/1.2kV IGBT) ST20 ANPC (1.2kV IGBT)

- ST10: 8.9 x 25cm
- Losses: ~13900W
- Total module area: ~1300cm²

900W/cm²

• ST20: 10 x 14cm

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0

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- Losses: ~9800W
- Total module area: ~1300cm²

800W/cm²

ST20 2-level (2kV SiC)

- ST20: 10 x 14cm
- Losses: ~7600W
- Total module area: ~400cm²

2400W/cm²



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Summary of Key Points



Energy storage is important

- Critical for grid reliability and facilitating renewable energy integration
- SD's innovations meet growing demand for efficient energy management



2kV SiC module advantages

- Design simplicity
- Increased efficiency
- Meets 1500V applications



Semikron Danfoss supports advancing innovation

- A leader in 2kV SiC
- Growing SiC portfolio
- Multiple chip suppliers
- Leading packaging technologies





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